

## Abstract of the Disclosure

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A surface mountable chip type semiconductor device comprises: first and second conductive land areas which are formed on an insulating substrate and which are electrically coupled with each other; a conductive post formed on the first conductive land area; and a semiconductor pellet which has electrodes on both sides thereof and which is mounted on the second conductive land area. A main area of the insulating substrate including the conductive post and the semiconductor pellet is encapsulated by encapsulation resin. Top portions of the conductive post and an external electrode electrically coupled to the semiconductor pellet are exposed from the encapsulation resin. Top surfaces of the conductive post and the external electrode are approximately coplanar with each other.